

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A high strength titanium copper alloy consisting of Ti at 2.0% by mass or more to 3.5% by mass or less;

the balance of copper and inevitable impurities; and

the average grain size of ~~20  $\mu$ m or less~~ 5 to 15  $\mu$ m;

the alloy further comprising a 0.2% proof stress expressed by "b" of 800 N/mm<sup>2</sup> or more; an electrical conductivity of 13.2% IACS or more; and

a bending radius ratio (bending radius/sheet thickness) not causing cracking as expressed by "a" by a W-bending test ~~based on Japanese Industrial Standard H 3110~~ in a transverse direction to a rolling direction;

wherein "a" and "b" satisfy  $a \leq 0.05xb - 40$ .

2. (Withdrawn) A high strength titanium copper alloy consisting of Ti at 2.0% by mass or more to 3.5% by mass or less;

at least one of Zn, Cr, Zr, Fe, Ni, Sn, In, Mn, P, and Si at 0.01% by mass or more to 3.0% by mass or less in total; and

the balance of copper and inevitable impurities;

the alloy further comprising an average grain size of 20  $\mu$ m or less;

a 0.2% proof stress expressed by "b" of 800 N/mm<sup>2</sup> or more; and

a bending radius ratio (bending radius/sheet thickness) not causing cracking as expressed by "a" by a W-bending test in a transverse direction to a rolling direction;

wherein "a" and "b" satisfy  $a \leq 0.05xb - 40$ .

3. (Original) The high strength titanium copper alloy according to claim 1, wherein the average grain size is in a range of 3 to 20  $\mu$ m.

4. (Original) The high strength titanium copper alloy according to claim 1, wherein the titanium copper alloy is obtained by performing final recrystallization annealing at a temperature below a borderline of an  $\alpha$ -phase and an  $\alpha$ +Cu<sub>3</sub>Ti phase.

5. (Withdrawn) The high strength titanium copper alloy according to claim 2, wherein the titanium copper alloy is obtained by performing final recrystallization annealing at a temperature below a borderline of an  $\alpha$ -phase and an  $\alpha$ +Cu<sub>3</sub>Ti phase.

6. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 1, characterized by performing final recrystallization annealing at a temperature below a borderline of an  $\alpha$ -phase and an  $\alpha$ +Cu<sub>3</sub>Ti phase.

7. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 2, characterized by performing final recrystallization annealing at a temperature below a borderline of an  $\alpha$ -phase and an  $\alpha$ +Cu<sub>3</sub>Ti phase.

8. (Withdrawn) The manufacturing method for a high strength titanium copper alloy according to claim 6;

wherein the alloy is cooled, after final recrystallization annealing, at a cooling rate of 100°C/sec or more;

cold worked at a working ratio of 5 to 70%; and

subjected to an aging process for 1 hour or more to 15 hours or less at a temperature of 300°C or more to 600°C or less.

9. (Withdrawn) The manufacturing method for a high strength titanium copper alloy according to claim 7;

wherein the alloy is cooled, after final recrystallization annealing, at a cooling rate of 100°C/sec or more;

cold worked at a working ratio of 5 to 70%; and

subjected to an aging process for 1 hour or more to 15 hours or less at a temperature of 300°C or more to 600°C or less.

10. (Original) A terminal connector using a high strength titanium copper alloy according to claim 1.

11. (Withdrawn) A terminal connector using a high strength titanium copper alloy according to claim 2.

12. (Currently Amended) A high strength titanium copper alloy which is subjected to an aging process after press working, the alloy consisting of:

Ti at 2.0% by mass or more to 3.5% by mass or less; and

the balance of copper and inevitable impurities;

the alloy further comprising a grain size of 5 to 15  $\mu\text{m}$ ; and

an electrical conductivity of 13.2% IACS or more;

wherein cracking does not occur by a W-bending test ~~based on Japanese Industrial Standard H-3110~~ in a transverse direction to a rolling direction with a bending radius of zero before the aging process, and the hardness of the worked matrix after the aging process is 300 Hv or more.

13. (Withdrawn) A high strength titanium copper alloy which is subjected to an aging process after press working, the alloy consisting of:

Ti at 2.0% by mass or more to 3.5% by mass or less;

at least one of Zn, Cr, Zr, Fe, Ni, Sn, In, Mn, P, and Si at 0.01% by mass or more to 3.0% by mass or less in total; and

the balance of copper and inevitable impurities;

the alloy further comprising a grain size of 5 to 15  $\mu\text{m}$ ;

wherein cracking does not occur by a W-bending test in a transverse direction to a rolling direction with a bending radius of zero before the aging process, and the hardness of the worked matrix after the aging process is 300 Hv or more.

14. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 12, comprising the steps of:

performing final recrystallization annealing at a temperature below a borderline of an  $\alpha$ -phase and an  $\alpha$ +Cu<sub>3</sub>Ti phase to adjust the grain size to 5 to 15  $\mu$ m; and  
performing final cold rolling at a working ratio of 5 to 50%.

15. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 13, comprising the steps of:

performing final recrystallization annealing at a temperature below a borderline of an  $\alpha$ -phase and an  $\alpha$ +Cu<sub>3</sub>Ti phase to adjust the grain size to 5 to 15  $\mu$ m; and  
performing final cold rolling at a working ratio of 5 to 50%.

16. (Original) A terminal connector using a high strength titanium copper alloy according to claim 12.

17. (Withdrawn) A terminal connector using a high strength titanium copper alloy according to claim 13.

18. (Previously Presented) A high strength titanium copper alloy consisting of:  
Ti at 2.0% by mass or more to 3.5% by mass or less; and  
the balance of copper and inevitable impurities;  
the alloy further comprising a tensile strength of 1200 MPa or more obtained by cold rolling at a reduction ratio of 95% or more, and an electrical conductivity of 10% IACS or more.

19. (Withdrawn) A high strength titanium copper alloy consisting of:

Ti at 2.0% by mass or more to 3.5% by mass or less;

Zn at 0.05% by mass or more to 2.0% by mass or less;  
at least one of Cr, Zr, Fe, Ni, Sn, In, Mn, P, and Si at 0.01% by mass or more to 3.0% by mass or less in total; and  
the balance of copper and inevitable impurities;  
the alloy further comprising a tensile strength of 1200 MPa or more and an electrical conductivity of 10% IACS or more.

20. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 18, comprising the steps of:

hot rolling at a temperature of 600°C or more;  
cold rolling successively at a working ratio of 95% or more; and aging at a temperature of 340°C or more to less than 480°C for 1 hour or more to less than 15 hours while maintaining an agglomerated matrix after the cold rolling.

21. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 19, comprising the steps of:

hot rolling at a temperature of 600°C or more;  
cold rolling successively at a working ratio of 95% or more; and aging at a temperature of 340°C or more to less than 480°C for 1 hour or more to less than 15 hours while maintaining an agglomerated matrix after the cold rolling.

22. (Original) A fork-shaped connector using a high strength titanium copper alloy according to claim 18.

23. (Withdrawn) A fork-shaped connector using a high strength titanium copper alloy according to claim 19.

24. (Previously Presented) A high strength titanium copper alloy which is subjected to cold rolling at a reduction ratio of 95% or more, and an aging process after press working, the alloy consisting of:

Ti at 2.0% by mass or more to 3.5% by mass or less; and  
the balance of copper and inevitable impurities;  
the alloy further comprising a worked matrix having a hardness of 345 Hv or more after the aging process.

25. (Withdrawn) A high strength titanium copper alloy which is subjected to an aging process after press working, the alloy consisting of:

Ti at 2.0% by mass or more to 3.5% by mass or less;  
Zn at 0.05% by mass or more to 2.0% by mass or less;  
at least one of Cr, Zr, Fe, Ni, Sn, In, Mn, P, and Si at 0.01% by mass or more to 3.0% by mass or less in total; and  
the balance of copper and inevitable impurities;  
the alloy further comprising a worked matrix having a hardness of 345 Hv or more after the aging process.

26. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 24, comprising the steps of:

hot rolling at a temperature of 600°C or more; and  
cold rolling successively at a working ratio of 95% or more.

27. (Withdrawn) A manufacturing method for a high strength titanium copper alloy according to claim 25, comprising the steps of:

hot rolling at a temperature of 600°C or more; and  
cold rolling successively at a working ratio of 95% or more.

28. (Original) A fork-shaped connector using a high strength titanium copper alloy according to claim 24.

29. (Withdrawn) A fork-shaped connector using a high strength titanium copper alloy according to claim 25.